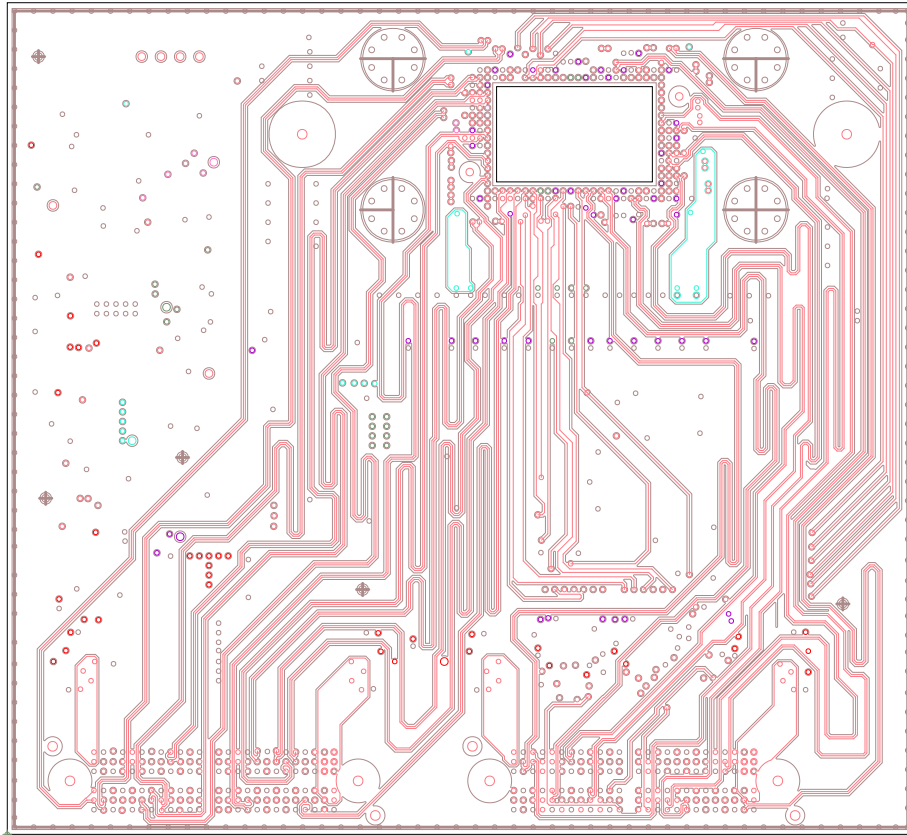
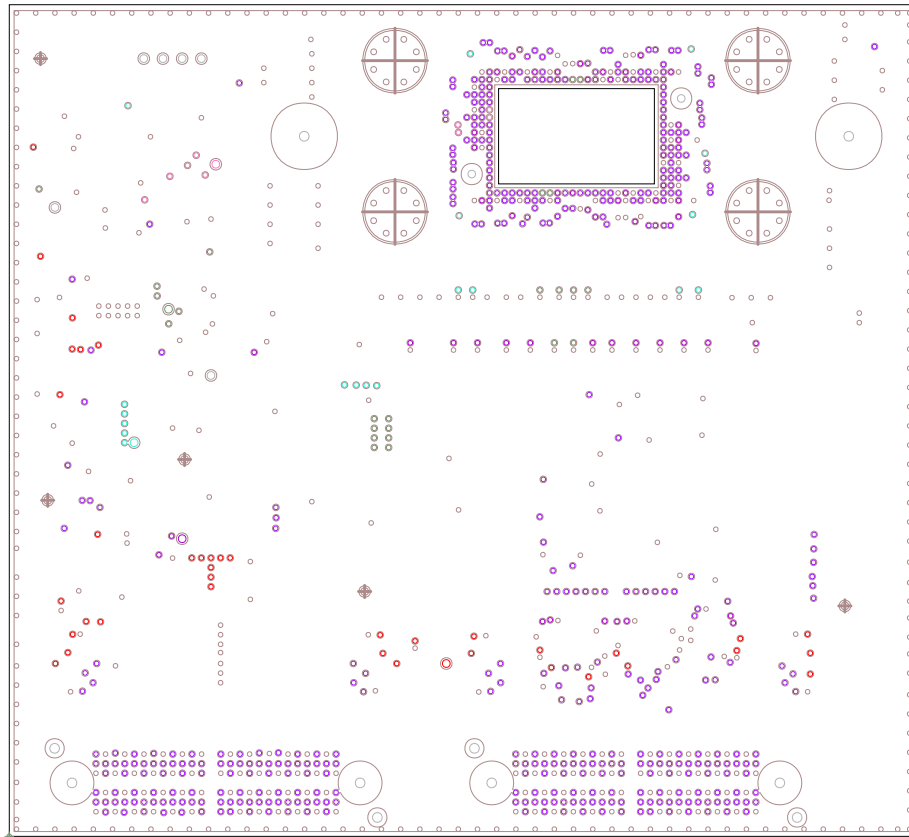


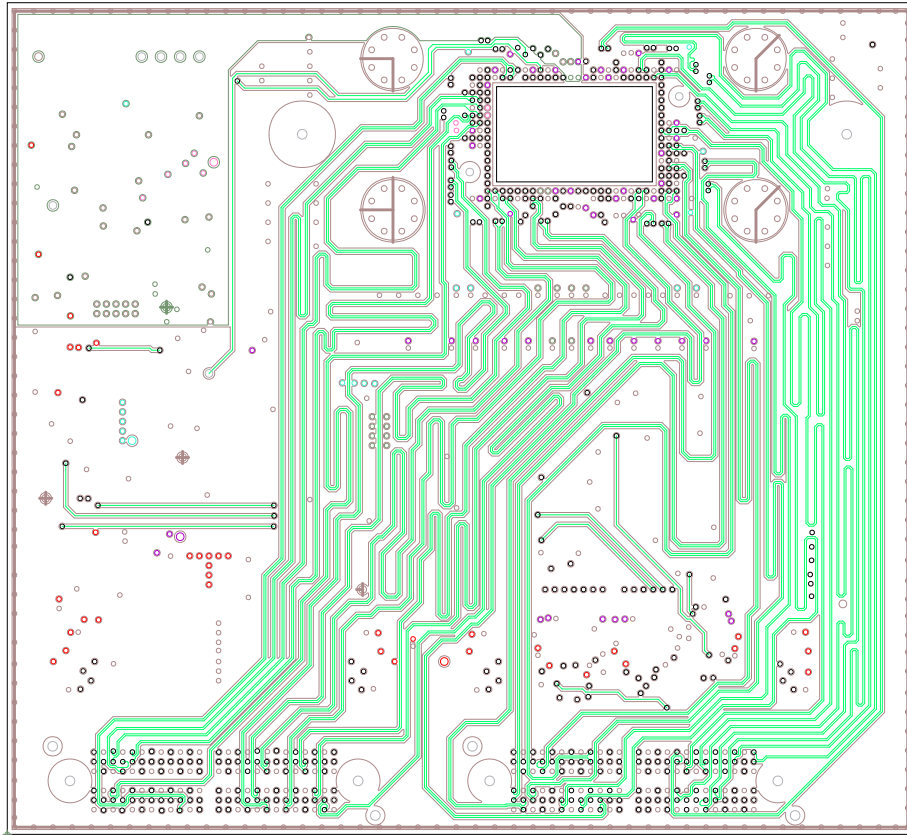
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BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION: ASSEMBLY SILKSCREEN - SECONDARY SIDE
PROJECT #:	DLP-65736	DATE: 29 SEP 2016 REVISION:



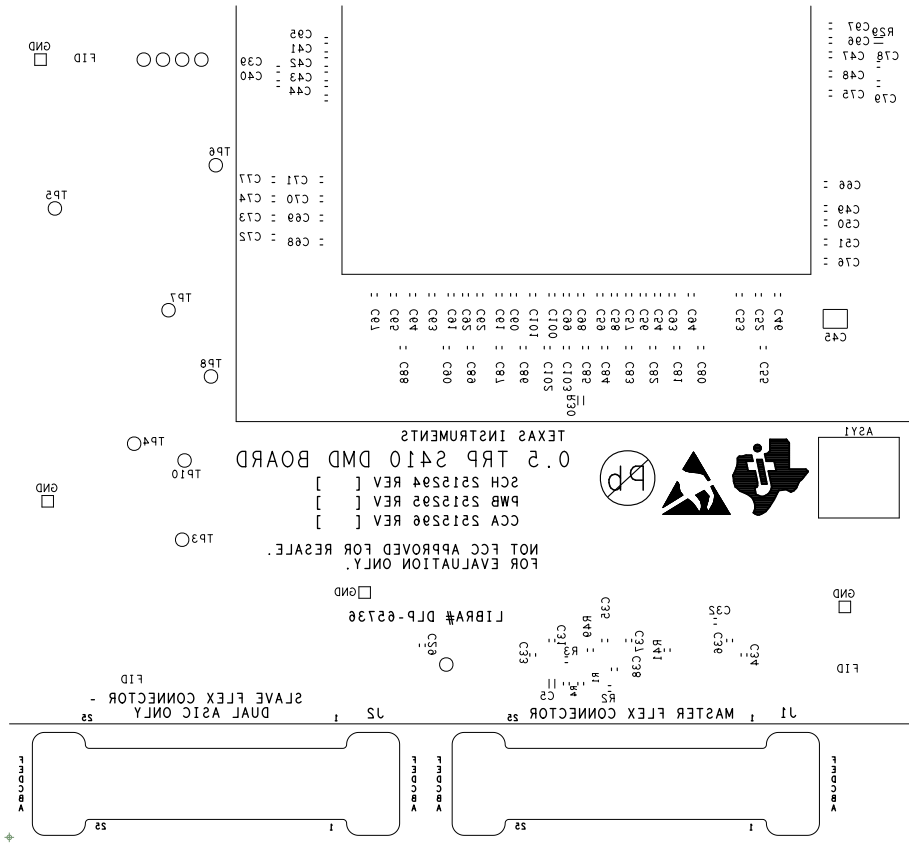
TI			
BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION:	Layer 4 - SIGNAL
PROJECT #:	DLP-65736	DATE:	29 SEP 2016
		REVISION:	



TI			
BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION:	LAYER 3 - GND PLANE
PROJECT #:	DLP-65736	DATE:	29 SEP 2016
		REVISION:	

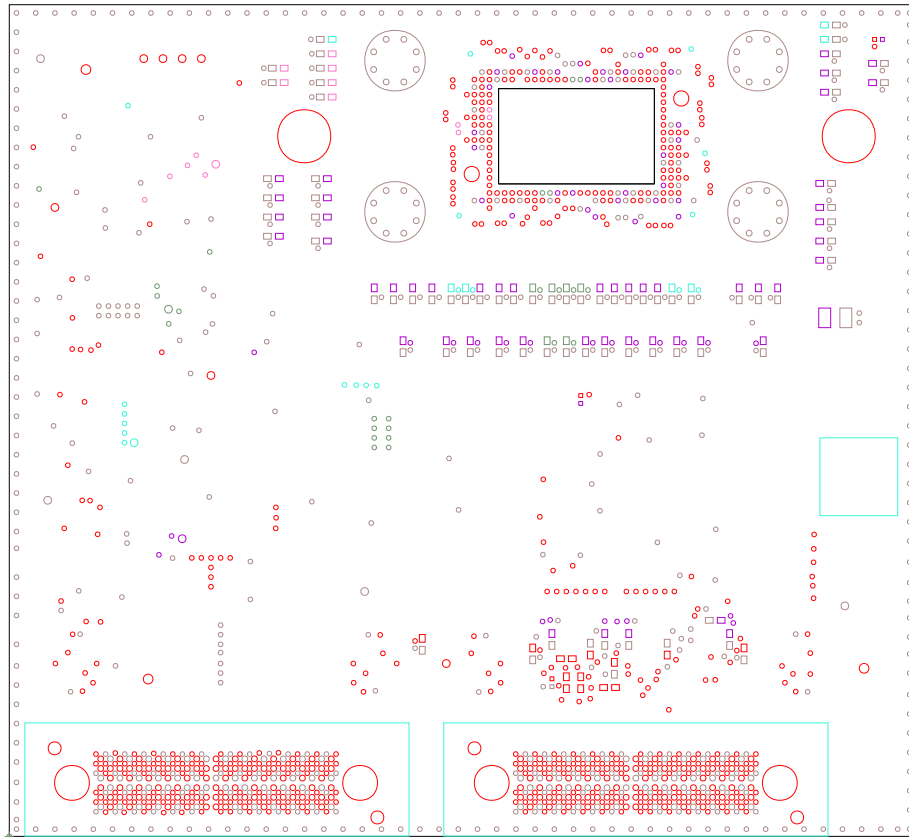


TI			
BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION:	Layer 2 - SIGNAL
PROJECT #:	DLP-65736	DATE:	29 SEP 2016
		REVISION:	

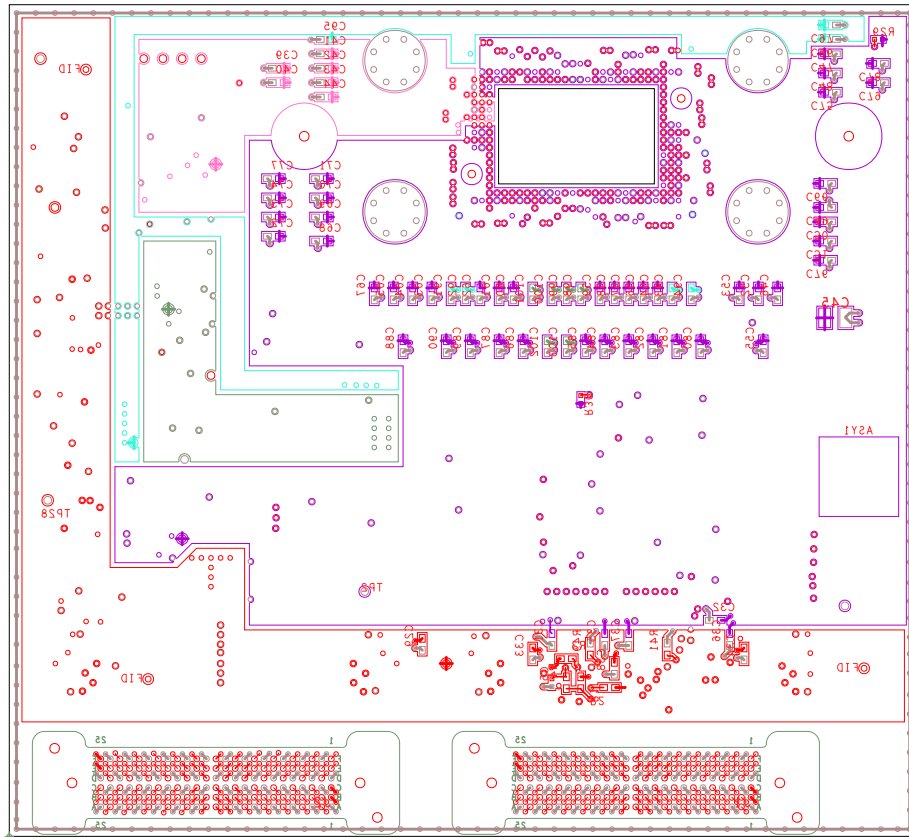


TI	
BOARD NAME:	0.5 TRP S410 DMD BOARD
DESCRIPTION:	SILKSCREEN - SECONDARY SIDE
PROJECT #:	DLP-65736
DATE:	29 SEP 2016
REVISION:	

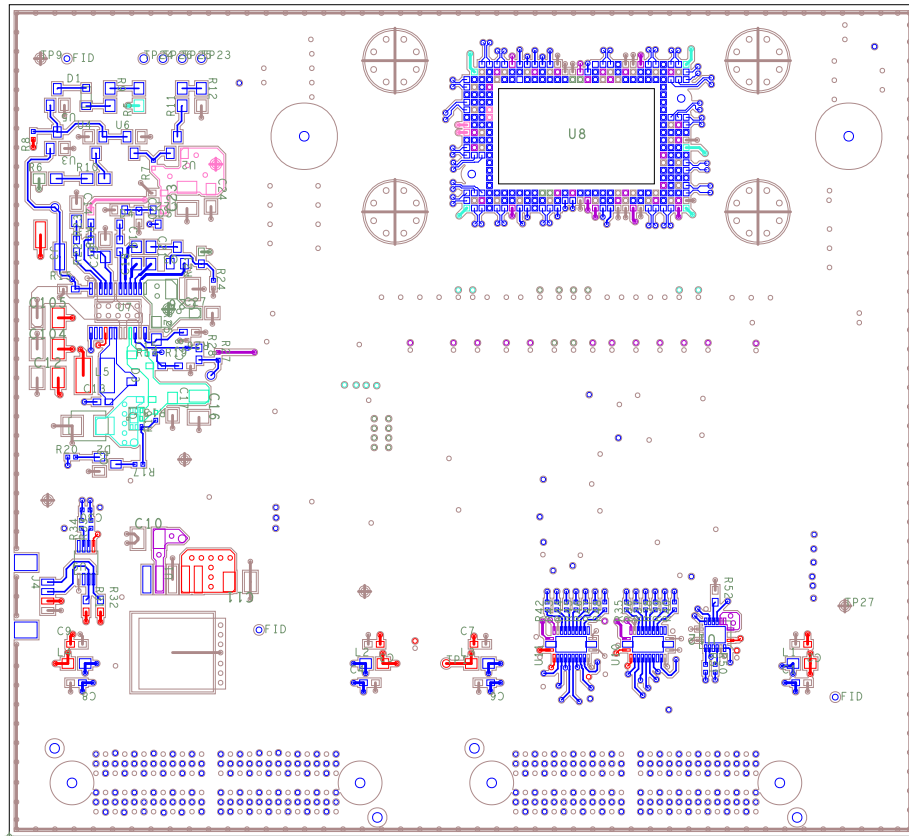




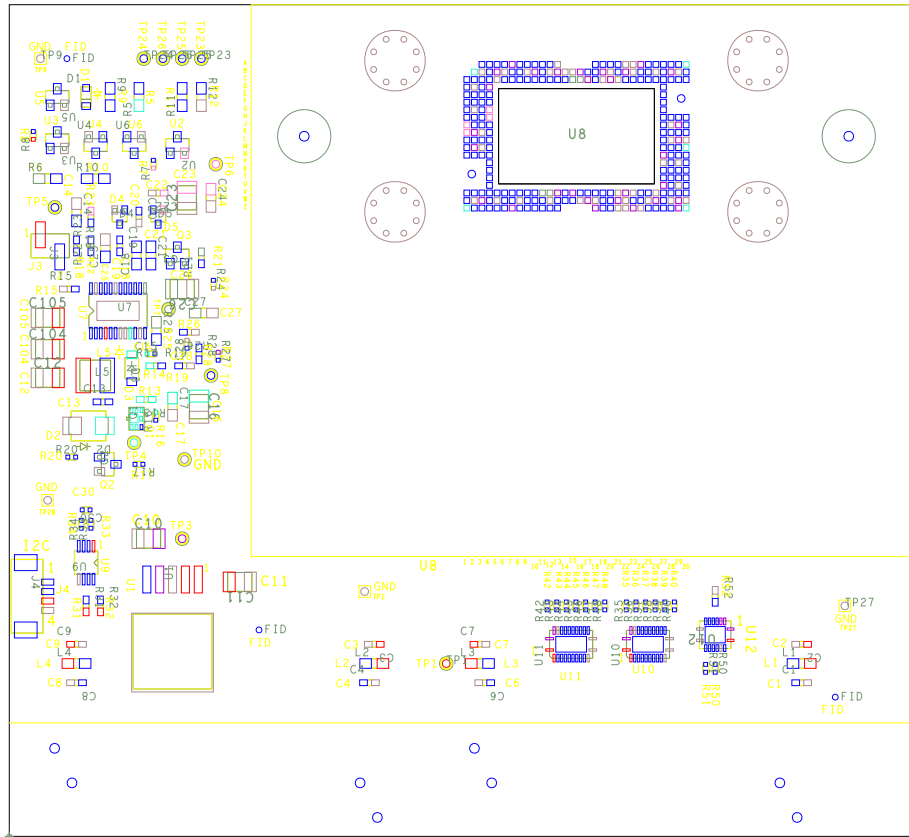
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BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION: SOLDERMASK - SECONDARY SIDE
PROJECT #:	DLP-65736	DATE: 29 SEP 2016
		REVISION:



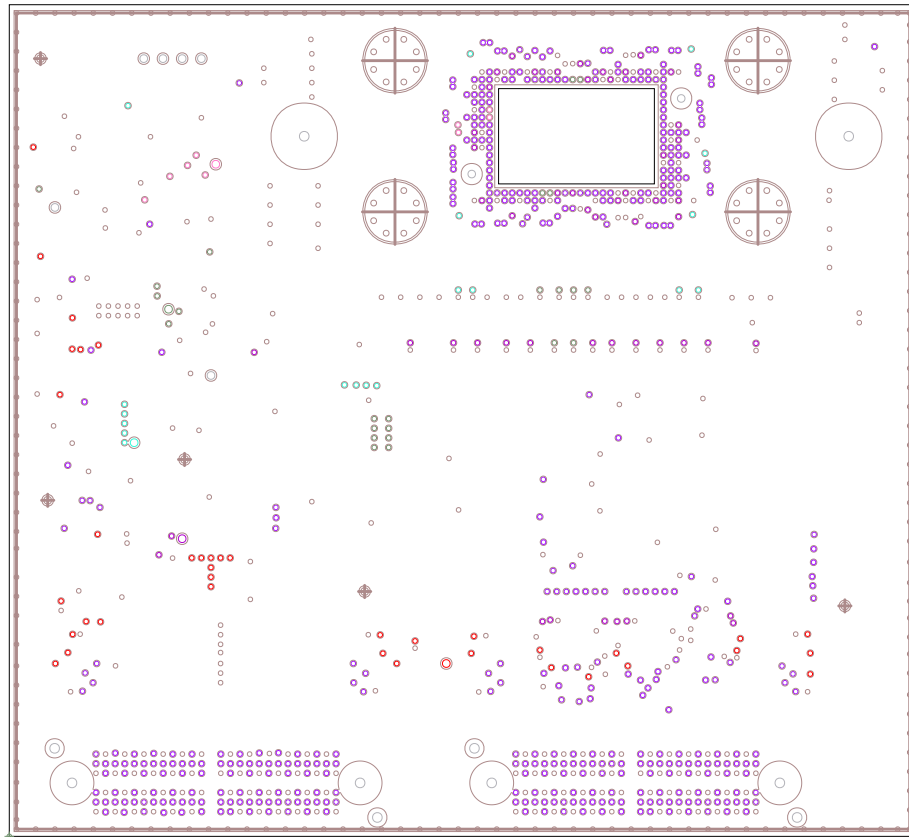
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BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION:	ASSEMBLY LAYER 6 - SECONDARY SIDE
PROJECT #:	DLP-65736	DATE:	29 SEP 2016
		REVISION:	



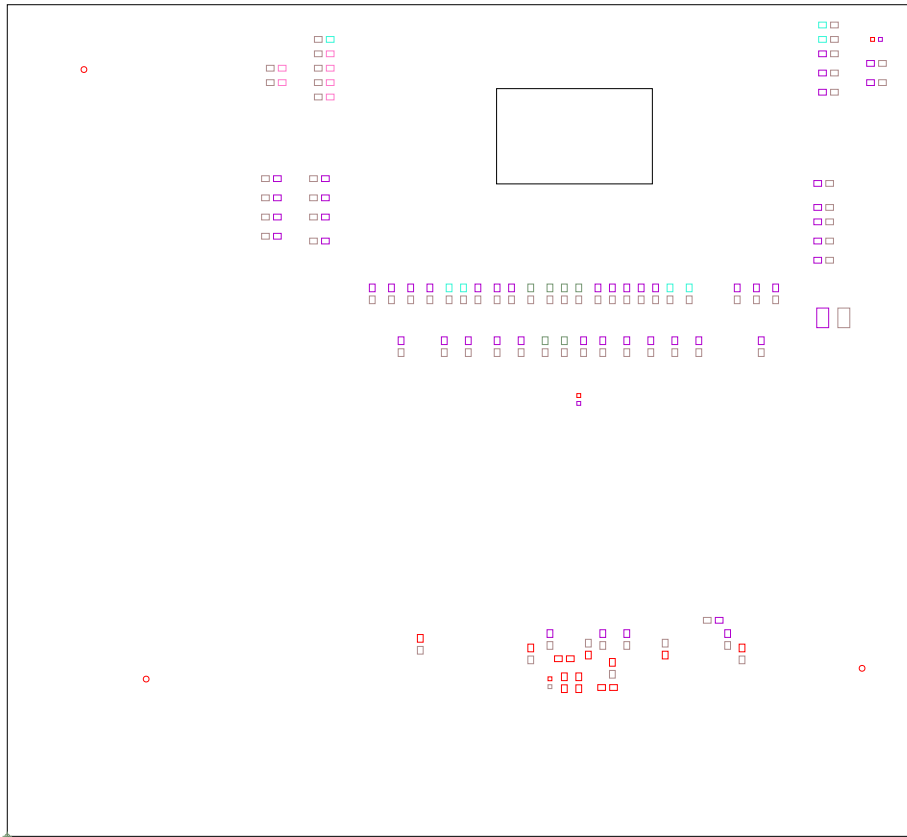
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BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION:	ASSEMBLY LAYER 1 - PRIMARY SIDE
PROJECT #:	DLP-65736	DATE:	29 SEP 2016
		REVISION:	



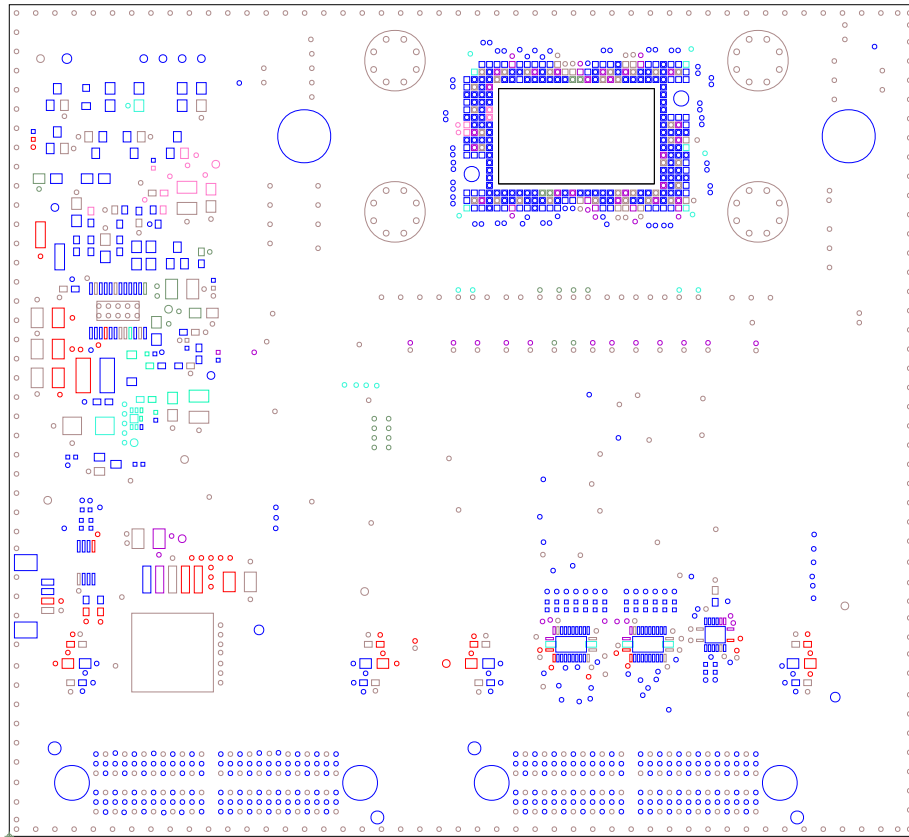
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BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION:	ASSEMBLY SILKSCREEN - PRIMARY SIDE
PROJECT #:	DLP-65736	DATE:	29 SEP 2016
		REVISION:	



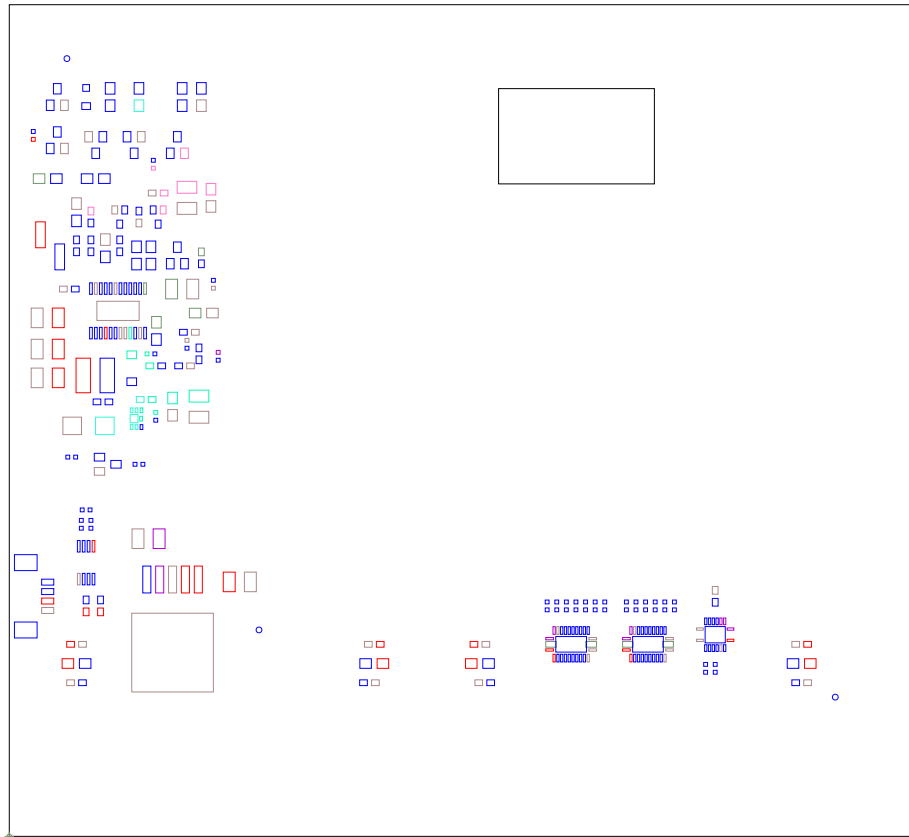
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BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION:	LAYER 5 - GND PLANE
PROJECT #:	DLP-65736	DATE:	29 SEP 2016
		REVISION:	



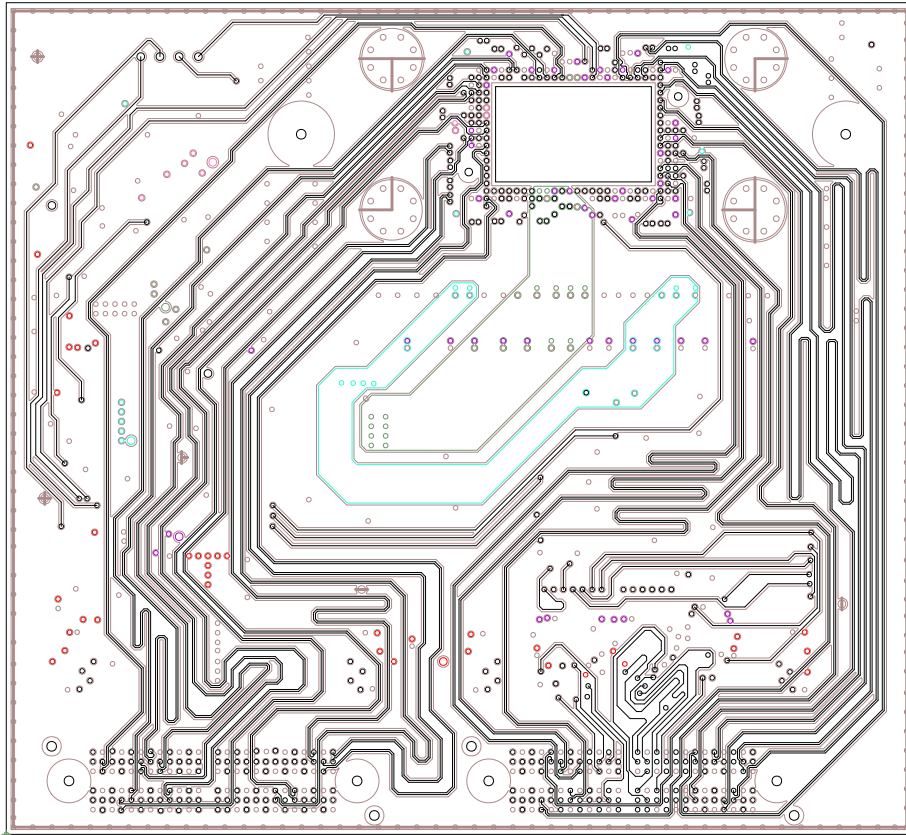
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BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION:	SOLDERPASTE - SECONDARY SIDE
PROJECT #:	DLP-65736	DATE:	29 SEP 2016
		REVISION:	



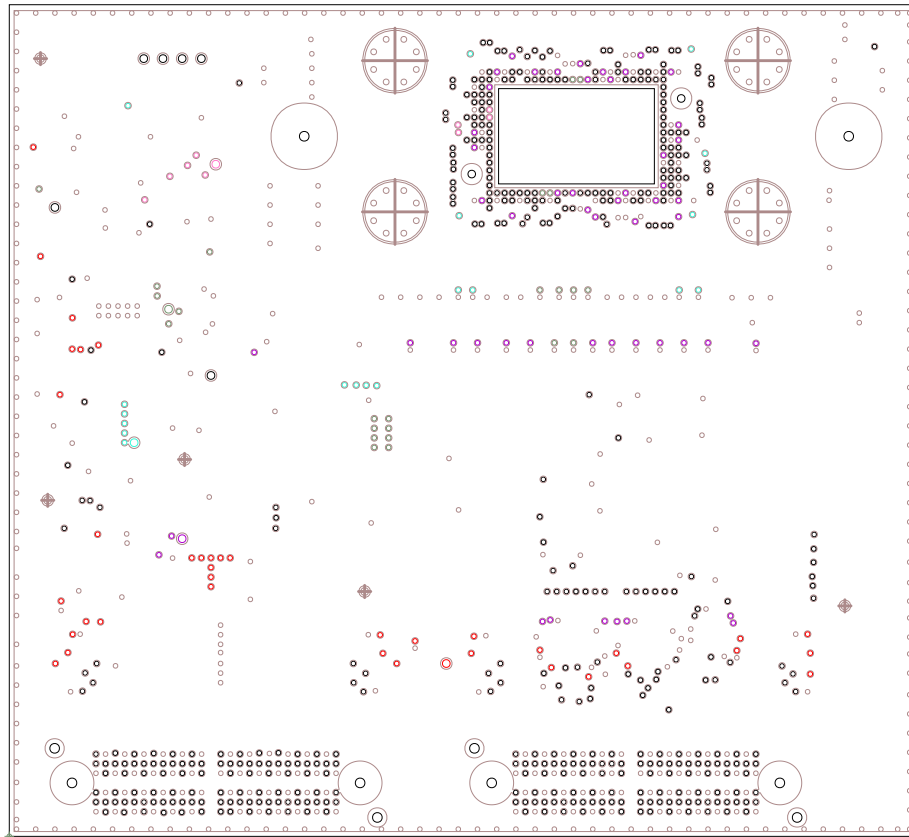
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BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION: SOLDERMASK - PRIMARY SIDE
PROJECT #:	DLP-65736	DATE: 29 SEP 2016
		REVISION:



TI			
BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION: SOLDERPASTE - PRIMARY SIDE	
PROJECT #:	DLP-65736	DATE: 29 SEP 2016	REVISION:



TI			
BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION:	Layer 6 - SIGNAL
PROJECT #:	DLP-65736	DATE:	29 SEP 2016
		REVISION:	



TI			
BOARD NAME:	0.5 TRP S410 DMD BOARD	DESCRIPTION:	LAYER 7 - GND PLANE
PROJECT #:	DLP-65736	DATE:	29 SEP 2016
		REVISION:	

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